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The management group of the on-chip bus standard OCP moves towards the formulation of an on-chip interconnect version of Dhrystone [Revised]

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The management group of the on-chip bus standard OCP (Open Core Protocol), the OCP IP (Open Core Protocol International Partnership), is aiming, by the second half of 2007, to formulate a benchmark standard for the evaluation of on-chip wiring performance. Mr. Ian R. Mackintosh, Chairman and President of the OCP IP, has clarified matters. There is to be an on-chip wiring (interconnect) version of Dhrystone, used as a benchmark standard for the evaluation of CPU operational performance. According to Mr. Ian R. Mackintosh of the OCP IP, "At present, total chip performance is determined in the same way as interconnect performance between cores. Given this situation, it is necessary for there to be some sort of benchmark for the on-chip interconnect".



Mr. Ian R. Mackintosh,
Chairman and President of the
OCP IP

According to Mr. Mackintosh, as well as the formulation of an on-chip interconnect standard, there are plans for a related seminar to be held and for a white paper to be drafted.

[Revision] When this article was originally published, reference was erroneously made to "Drystone" instead of "Dhrystone". We apologise for this, and the content of this article has now been revised.

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